EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("20020045146").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 12:56
S2	1	10/577145	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/20 13:00
S4	14	("5517594" | "5616264" | "5661669" | "5739505" | "5895596" | "6041172").PN. OR ("6803548").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/09/20 13:12
S3	1	(09/950876).APP.	USPAT; USOCR	OR	ON	2009/09/20 13:12
S5	4	((("20030061989") or ("20040087185") or ("20060258170") or ("20050028738")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 13:17
S6	1	("6730885").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 13:27
S7	1	("5517594").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/09/20 13:30
S10	779131	((156/345.$) or (118/7$) or (315/111.$)).CCLS. or ((("216") or ("427") or ("438") or ("134") or ("204") or ("219") or ("392")).CLAS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/15 17:00
S9	11882	((118/715) or (118/722) or (118/724) or (118/725) or (156/345.51) or (156/345.52)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/15 17:00
S8	4842	((118/724) or (118/725)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/15 17:00
S12	1425952	(control$4 feedback feed adj back) with (thermal$3 heat$3 temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:01

S11	1197569	(sens$4 measur$5 detect $4) with (thermal$3 heat $3 temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:01
S13	1245880	(load$3 unload$3 remov$4 tak$3 near2 out) with (wafer substrate object workpiece work adj piece semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:02
S14	342	S8 and S11 and (S12 same S13)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:03
S16	110	S9 and S11 and (S12 same S13) not S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:04
S15	29423	(forecast$3 predict$3) with (thermal$3 heat$3 temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:04
S18	103	S17 not S14 not S16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:05
S17	129	S10 and S11 and S15 and (S12 same S13)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:05
S19	403	(sens$4 measur$5 detect $4) near5 (thermal$3 heat $3 temperature) and (control$4 feedback feed adj back) near5 (thermal $3 heat$3 temperature) and (load$3 unload$3 remov$4 tak$3 near2 out) near5 (wafer substrate object workpiece work adj piece semiconductor)	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/15 17:06
S21	40	(park near2 youngchul kawamura near2 kazuhiro wang near2 wenling).in.	US-PGPUB; USPAT	OR	ON	2009/10/15 17:07

S20	510	((sens$4 measur$5 detect$4) near5 (thermal$3 heat$3 temperature) and (control$4 feedback feed adj back) near5 (thermal$3 heat$3 temperature) and (load$3 unload$3 remov$4 tak$3 near2 out) near5 (wafer substrate object workpiece work adj piece semiconductor)).clm.	US-PGPUB; USPAT	OR	ON	2009/10/15 17:07
S23	44	(S21 S22) and S20	US-PGPUB; USPAT	OR	ON	2009/10/15 17:09
S22	5662	(tokyo adj electron).as.	US-PGPUB; USPAT	OR	ON	2009/10/15 17:09
L12	1	wo-03041139-$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 09:35
L13	4	(sens$4 measur$5 detect$4) near5 (thermal$3 heat$3 temperature) and (control$4 feedback feed adj back) near5 (thermal$3 heat$3 temperature) and (load$3 unload$3 remov$4 tak$3 near2 out) near5 (wafer substrate object workpiece work adj piece semiconductor) and heat$4 near5 wall	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 09:47
L20	2650	(tower cassette boat) near10 (wafer substrate workpiece work adj piece object) and (heat$4) near10 (exhaust$3 discharg$3 outlet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 10:39
L23	134	22 and (exhaust$3 discharg$3 outlet) near10 (upper top ceiling roof lid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 10:40
L22	243	20 and L21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 10:40

L21	4842	((118/724) or (118/725)).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/16 10:40
L27	2	jp-2002025997-$.did. jp-2002-091574-$.did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 11:54
L26	0	jp-2002-025997	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/16 11:54
L28	1	("20030019585").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/10/16 14:03

10/16/09 3:37:48 PM
C:\ Documents and Settings\ marancibia\ My Documents\ EAST\ Workspaces\ 10577145 Thermal modeling.wsp